# ND280upgrade WP1 Mechanics Workshop Summary

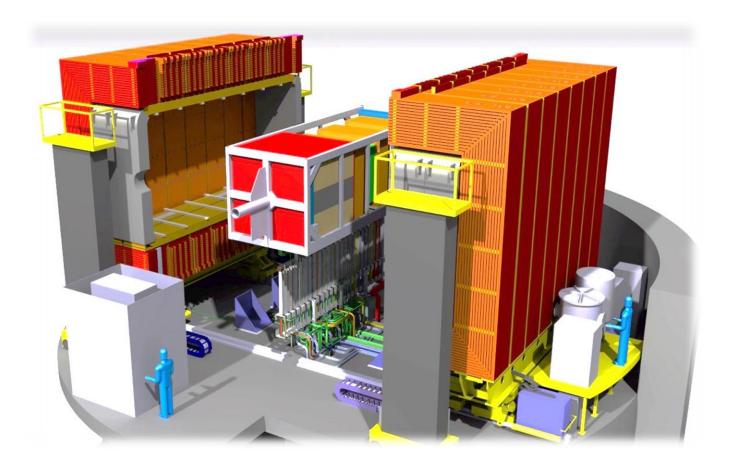
**Thorsten Lux** 



# Tasks of this workshop

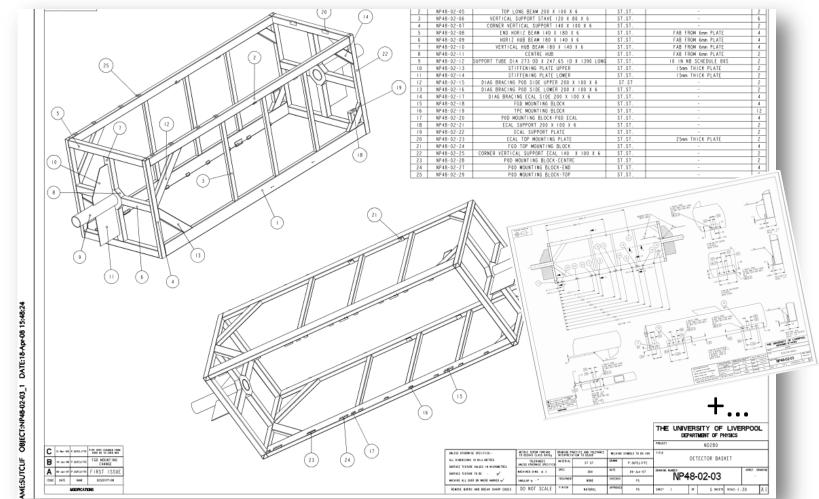
- Define a list of urgent questions to be addressed concerning the mechanics and integration tasks eg
  - Set up a 3D model of the basket with the new detectors (see F. Cadoux)
  - Define the detector envelopes (needed for detector design)
  - Specs of the support structure inside the basket, and interfaces with the basket
  - Specs of the TOF support structure and interfaces with the barrel ECAL and magnet
  - First discussion about accessibility of detectors and electronics (do we need to remove the top TPC ?)
  - First discussion about the services routing
  - First discussion about the integration plan and schedule
- Define the team and the work plan
- Allow discussions and interactions between the various groups
- Plan for the preparation of the TDR (see Thorsten)
- If time allows, discussion about the prototypes

by F. Cadoux (Uni. Geneve)





## Overview of the current situation



Thanks to *Peter Sutcliffe (Liverpool)*, basket fabrication dwgs are all available (needed for modifs)

New Detectors into the basket



## Overview of the current situation

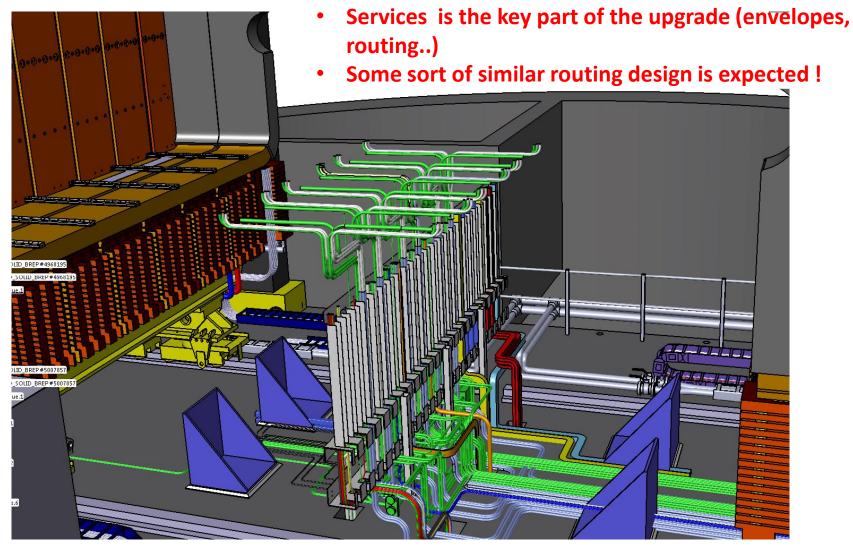


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New Detectors into the basket



## Overview of the current situation



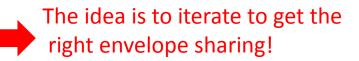
New Detectors into the basket

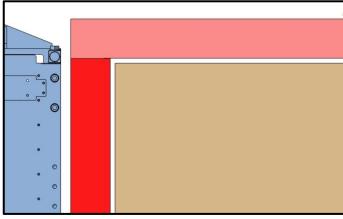


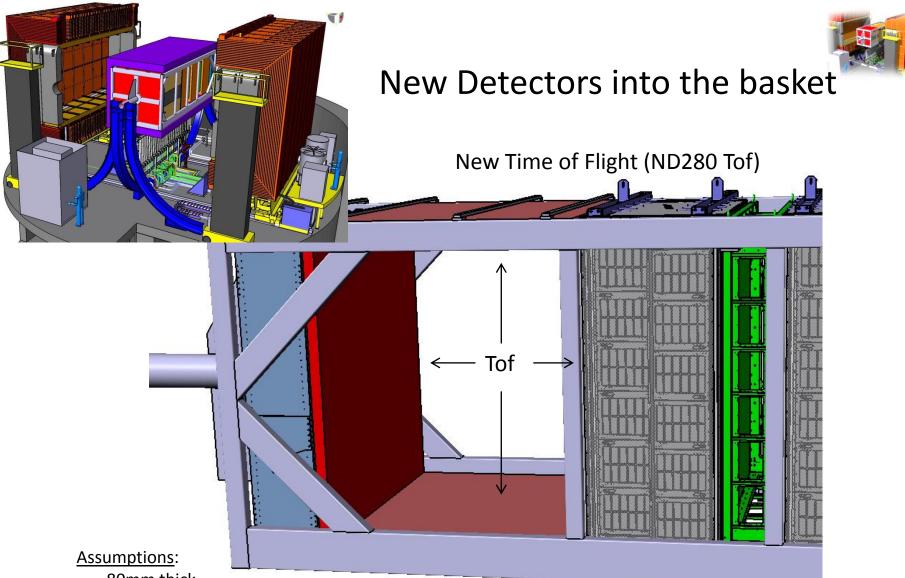
Before showing the CAD designs...

...Rules to define the Detector envelopes (TB Discussed):

- Each detector volume includes: sensitive parts, frames, <u>some</u> services & readout system... like the current ones.
- **10mm** gap is assumed between detectors "blocs" to account for deformations, insertion, handling...and more margin of safety!
- Brackets, fixation points are not considered yet
- ToF overall thickness (80mm) is given as a starting point...

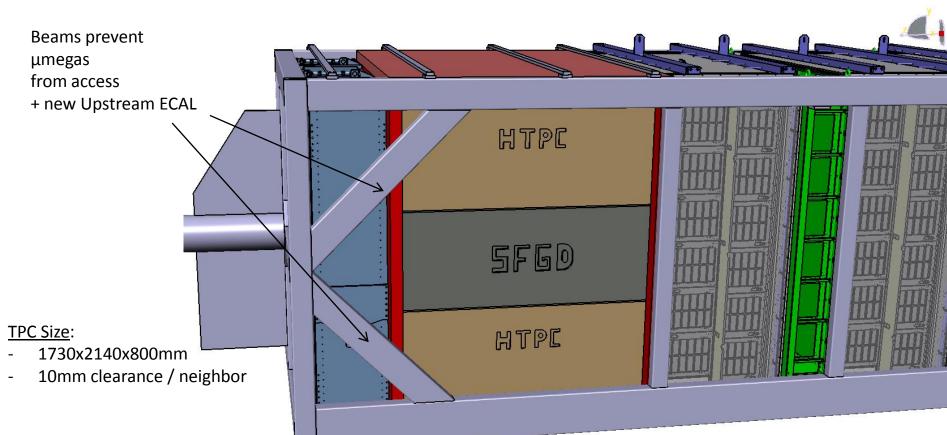






- 80mm thick
- Design with fixation INSIDE Basket frame
- 2 sides not shown (in total 6 sides: 2230x2320x80mm / 2320x1910x80 / 2390x1910x80) -
- OPTION: Tof could be mounted OUTSIDE the Basket (careful with unprotected parts!)





#### Super FGD Size:

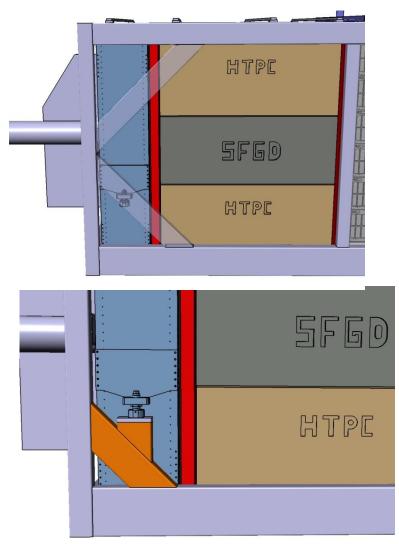
- 1730x2140x600mm

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- 10mm clearance / neighbor

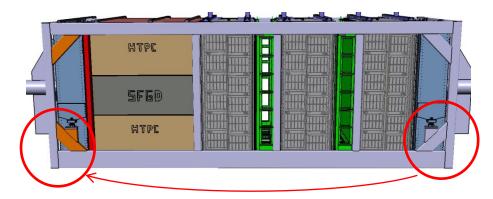
Upstream ECAL might be thinner in reality => actual CAD files will be provided





Clear the access for HTPC µmegas (oblique beams)

- Reuse the current beam sys for Downsteam ECAL (below)
- See next slide...





## Guidelines for I/F & Integration

- Clearly identify the <u>technical coordinator</u> for each part: HTPC, TOF, sFGD, Upstream ECAL, global services...
   Provide CAD models, and in case FEA's to the resp. for Integration
- Organize a sort of inner <u>Data Base</u> for the Upgrade in which the latest CAD versions are saved (to ease exchanges)... STEP model is OK for exchanges (even using the same software!!)
- Perform the <u>updated FEA</u> on the Basket with new config. (see wrt proposed modifs and new weights)
- <u>Services</u> are a key issue (as always!)...to be tackled soon! It may drive some design choices.
- To do so.. an Engineer is requested to take the lead on integration...
- Open question: Which basket modifications are possible and how can they be done in-situ?

# **TPC Field Cage**

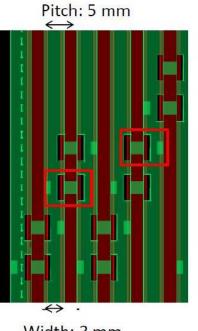
## Strip Design

- double sided
- mirror strips
- all resistors on inner side
- cut marks all 5 cm on inner side
- cross marks for alignment on mirror strip
- foil dimensions currently: ~55x220 cm

#### ILC TPC Design

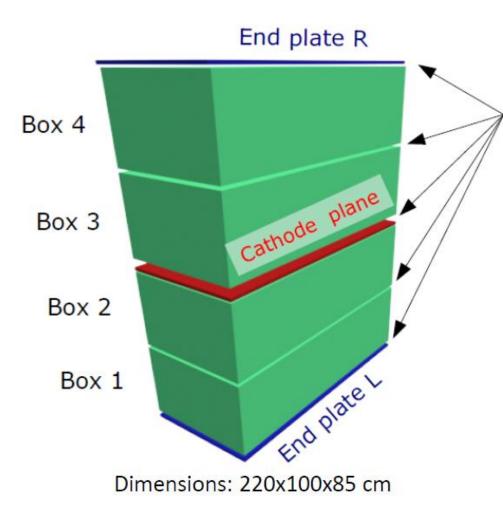


Figure 5.13: Resistor chain in the field cage at the central connection between the half boards



Width: 3 mm

# **TPC Field Cage**



- different concepts under consideration
  - 4 modules of 50 cm
  - 2 modules of 1 m
- discussions about gas tightness, HV stability, field quality, ... of options ongoing
- Fall back solution: 4 full size flat panels for construction

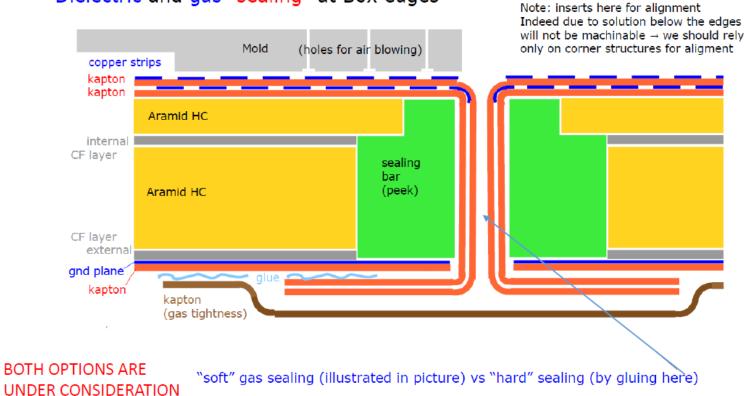
# **TPC Field Cage**

bores for joining boxes

Mechanical stiffness + alignment of strips of different Boxes provided by corner structures

- ? corner structure shape ?
- ? corner structure to be easility machined  $\rightarrow$  peek

#### Dielectric and gas "sealing" at Box edges



# **MM** Frame

### Prototype

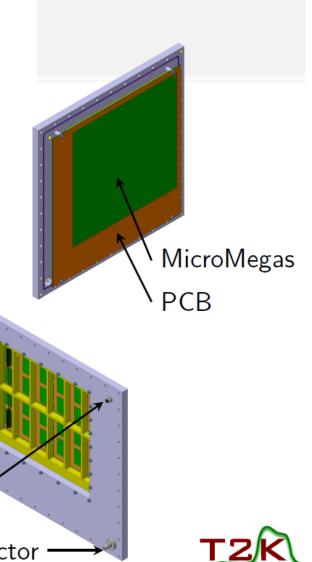
- Min. size of an available magnet ( $\phi$ 87 cm)
- Min. outer dimensions  $(50 \text{ cm} \times 50 \text{ cm})$ 
  - Current MicroMegas prototype (340 mm×357 mm)
  - PCB plate
  - Gas inlet / outlet
  - High voltage connector?

Our workshop

Milling machine (1000 mm×500 mm)

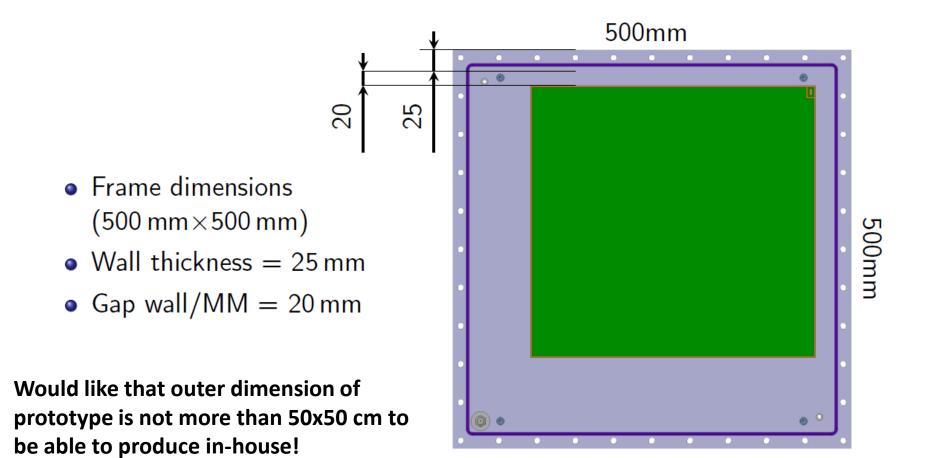
Gas connectors

HV connector



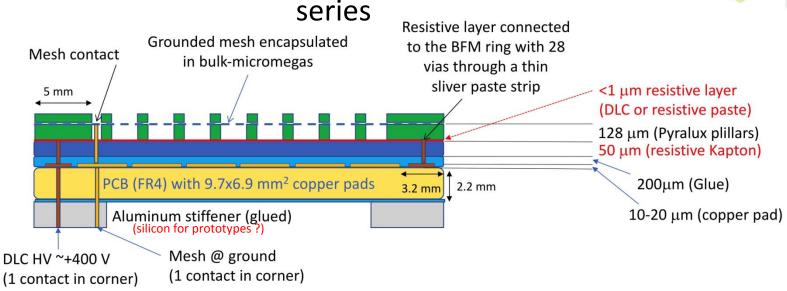


# **MM** Frame



## The resistive bulk-micromegas first prototype : MM0





The restive Kapton foil restivity should be **around 500 kOhm/square** for optimal charge spreading both resistivity and glue thickness to be adjusted for the desired pad function (sigma ~ 2,6 mm)

#### Four T2K/TPC PCBs were produced @ CERN : 2 were used to produce DLC bulk-micromegas 2 DLC kapton resitive bulk-micromegas prototype **MM0-DLC1 & 2** are finished and ready for tests with cosmics

MM0-DLC1 & MM0-DLC2 were done with a DLC kapton foil ordered for 2 Mohm/square : it was measured to be 2,5 Mohm/square and the 200°C annealing for 1 hour did not change this too high value ! (→ sigma ~ 1,3 mm)

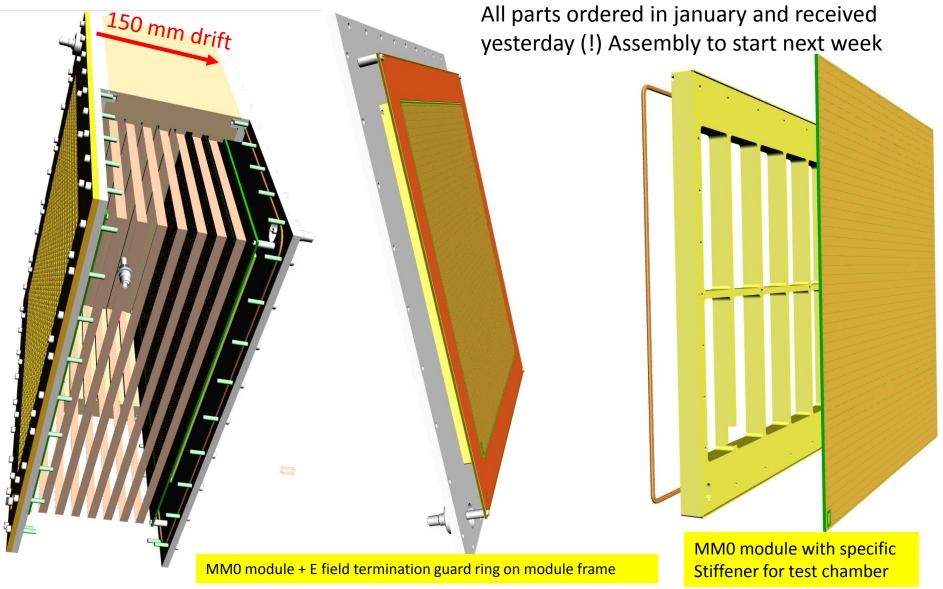
The 2 remaining PCBs will be used to realise 2 other prototypes

- with a ~500 kOhm/square screen-printed resistive paste layer on Kapton : MM0-SP1
- with a lower resistivity DLC Kapton if it can be achieved by the manufacturer (Japan)

from A. Delbart's talk

### **TEST CHAMBER FOR PROTOTYPE TESTS WITH COSMICS**





### RESISTIVE INK SCREEN-PRINTING FOR MM0-SP1 PROTOTYPE



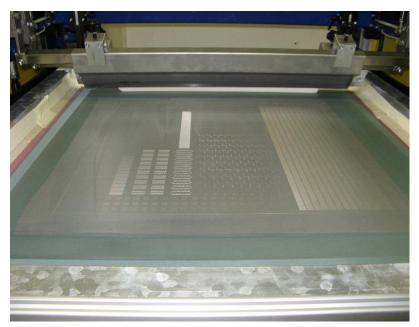
#### Screen-printing machine @ Irfu



 2 years experience in screen-printing of resistive inks on Kapton and glass for resistive micromegas and RPCs

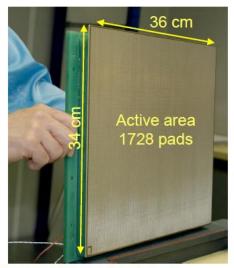
- Use of masks for pattern printings (such as mircomegas 250 µm strips)

- Up to 50x60 cm<sup>2</sup> surfaces were done



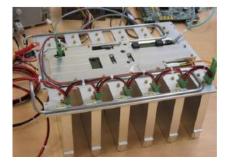
#### from D. Calvet's talk

## **TPC Electronics**



#### Micromegas detector

- 1726 active pads
- Rear-side: 24 \* 80-pin connectors,
  1.27 mm pitch (ERNI)





#### Front-End Card - FEC

- 288-channel; 6 cards per detector
- Perpendicular to detector
- 4 \* 80-pin connectors, right angle 1.27 mm pitch (ERNI)
- 1 \* 80-pin connector, right angle, Hirose, FX2

#### Assembled readout module

- Mechanics for precise positioning
- Shielding and water cooling
- $\rightarrow$  72 of these modules in operation since 2009

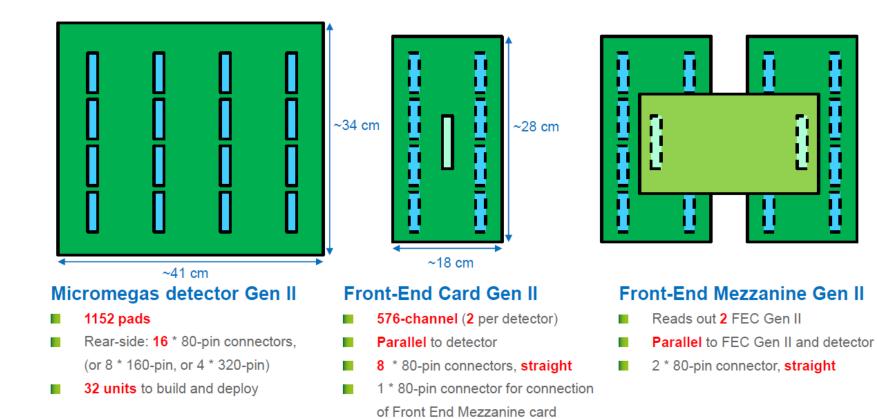


#### Front-End Mezzanine Card

- Reads out 6 FECs
- Perpendicular to FEC; parallel to detector
  - 6 \* 80-pin connectors, straight, Hirose FX2

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# **TPC Electronics**



#### Families of solutions for interconnection

Classical rigid connectors: simplest, but require precise positioning in multi-connector per board setup

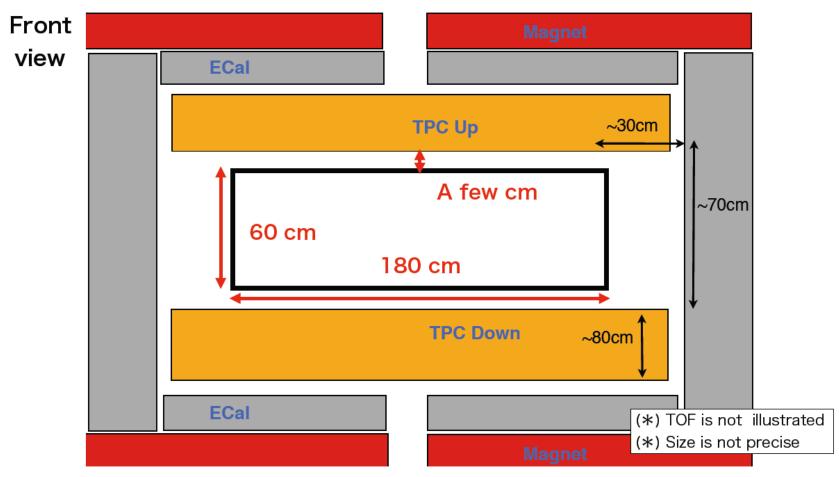
Floating connectors: less common products, structure of the connector absorbs misalignment in X and Y

Flexible conductors: misalignement absorbed by cables, flexible PCB, etc. Signal degradation, higher cost

## Placement of SuperFGD



5



To be integrated with other detectors in limited space (Please refer to Franck Cadoux's slide for available space in the basket)

# SuperFGD

## **General requirements in mechanics**

### What we have to archive:

- Mechanical robustness w/ easier assembly & integration
- Accurate & stable connections

### What we then have to challenge:

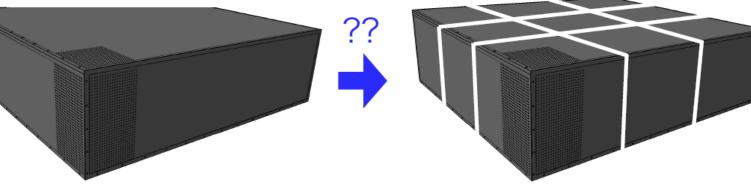
- Minimal material not to stop particles between cubes & TPC
- Minimal space for better acceptance between cubes & TPC
- Less noise & cooling system for electronics
- · Maintenance (e.g. Access to electronics in the basket)

### Goal of this talk:

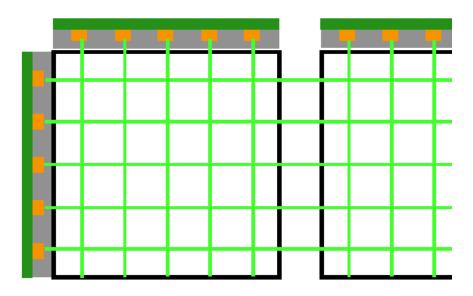
- To share current conceptual design & status based on past experience or other experiments
- To share preliminary prospects to make it reality
- $\rightarrow$  Start of discussion to optimize whole & interface structure
- ightarrow There could be better ideas. Feedbacks are welcome

Original idea was all cubes compressed in a container
 → Now assuming more realistic case with several modules

Original idea (no modularization) Assume more realistic case with several modules Modules w/ 60 x 60 x 60 as another option

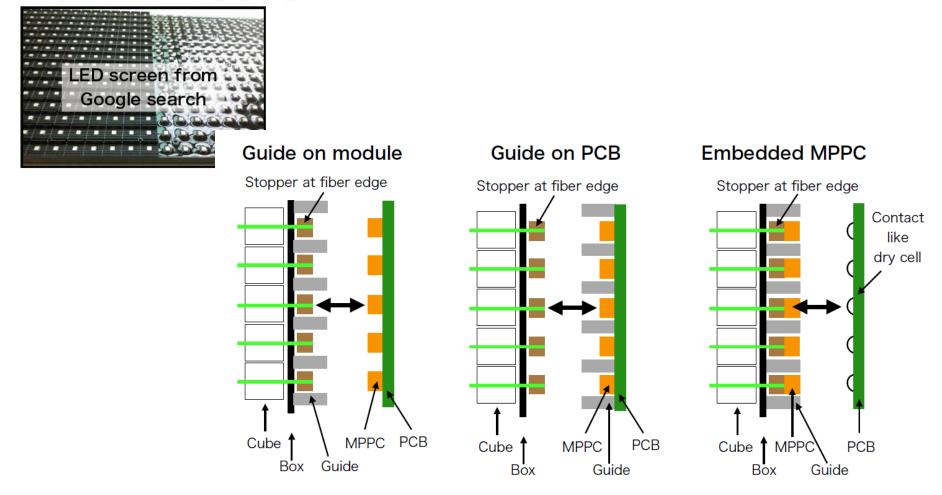


- discussion about problems of modular design
  - alignment to feed fiber through several modules
  - risk of damaging fibers in zone between modules



## Alignment of MPPC PCB + Fiber

An images of PCB panel (& guide)

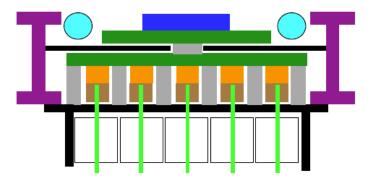


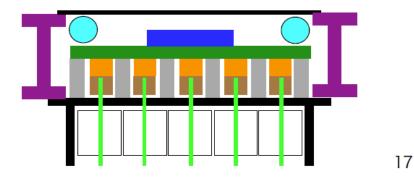
- How to fix fiber? Box design? Mechanical robustness?
  Small space & materials? Maintenance capability for MPPC/FEE?
  Light tightness?
  - $\rightarrow$  To be designed considering above

# Possible Design of the Frontend Card

### Possible design (To be discussed carefully)

- $\cdot$  2 PCB layers along with separated structure  $\rightarrow$  FGD-like structure
- 1 PCB layer of MPPC+FEE on same board → More aggressive design (Compact & less material but concerns in heating, light tightness and maintenance capability)





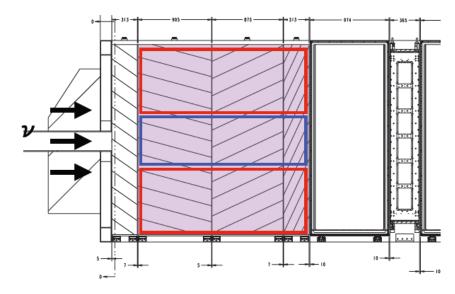
- In FGD, a water circulation system operating at sub-atmospheric pressure cools in the mini-cartes
- Chilled water flows through hollow aluminum extrusions mount on the inside of each I-beam

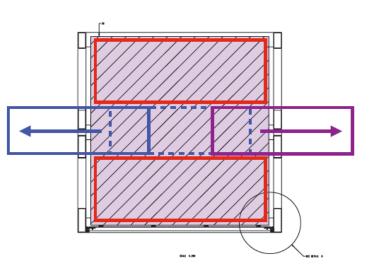
Amount of material and electrical power between target and TPC has to be carefully studied => talks at future WG1 sessions!

## **Option: Rail to take SuperFGD out?**

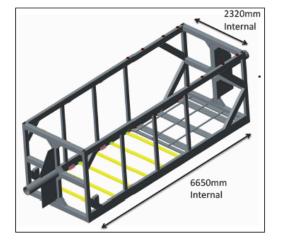
Side view

Front view





- Rail to take SuperFGD out from the basket for the access to electronics, MPPCs, etc…
- Several constraint to verify
  e.g. Difficulty to modify basket, TOF counter



## Things to be addressed

### When & how to access for maintenance?

- MPPC (e.g. Replacement "during Install" but "not after operation")
- Frontend (e.g. Replacement during "Install" or "Operation")
  - $\rightarrow$  We can fix design based on those constraint
  - $\rightarrow$  Installation & integration procedures are also to be considered

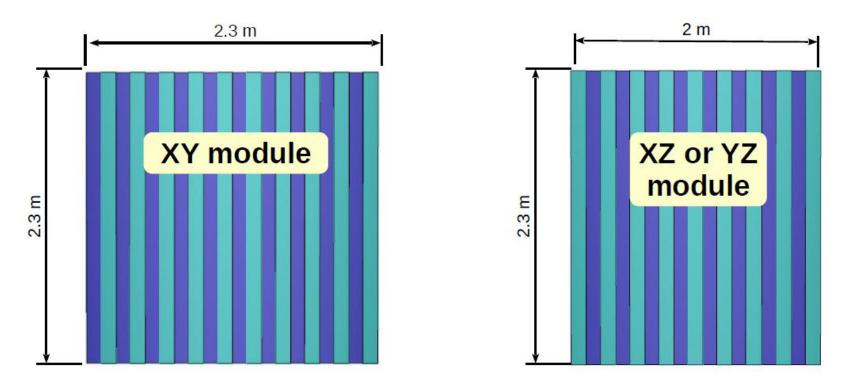
### Connection from frontend to backend?

- Cabling (routing & connector) & power supply are not yet considered
- $\cdot$  Hoses for water flow system is necessary if we want
  - $\rightarrow$  To be discussed with WP1

### Calibration?

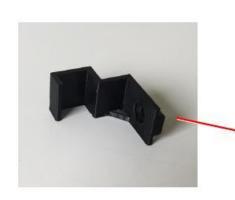
- Light injection system?
- Comics & Sand muons are enough?
  - $\rightarrow$  No dedicated study so far. Need to be addressed.

### **ToF modules**



- All bars are identical: 2.3 m x 12 cm x 1 cm
- In total: 3 modules XY + 4 modules XZ
- Total weight ~360 kg
- The ~5 mm overlap between bars was assumed
- At least 3 cm slit is requited for the installation

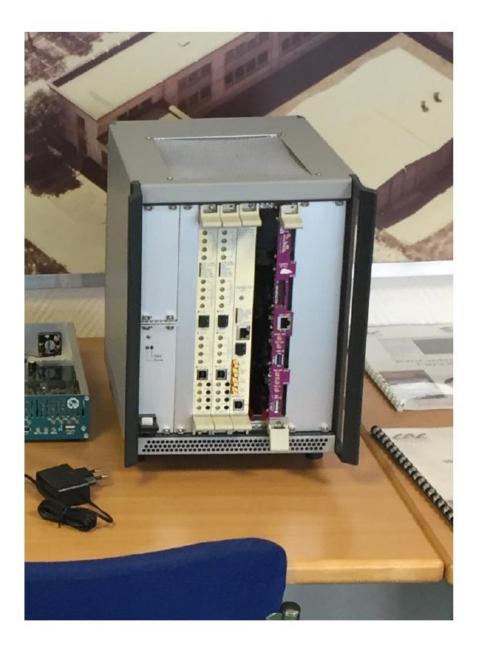
### The bar fixation used for the prototype



Multiple hooks should be foreseen (earthquake)







## DAQ system

- Electronics is developed in LAL (Dominique Breton)
- 16ch SAMPIC chip. All channels independent/self-triggered
- One crate is 256 ch = 64 ch x 4
  VME modules
- Is there space inside the basket? or we need to pull outside 256 cables for the analog signal
- If inside, the issue of cooling to be solved.

# Urgent tasks-1

- Get P0D Upstream Ecal CAD model
- Ask Liverpool engineers about modifications to the basket in situ
- Define TOF configuration
- Concept of support structure
- Define SuperFGD, TPC and TOF envelopes
- Define SuperFGD, TPC and TOF engineers (each responsible for CAD model of each detector)
- Set up a directory of ND280 Upgrade Internal Technical Notes
- Check availability in situ ("survey" team to Tokai in ~June ?)

• Define overall Integration engineer responsible for maintaining EDMS + CAD drawings

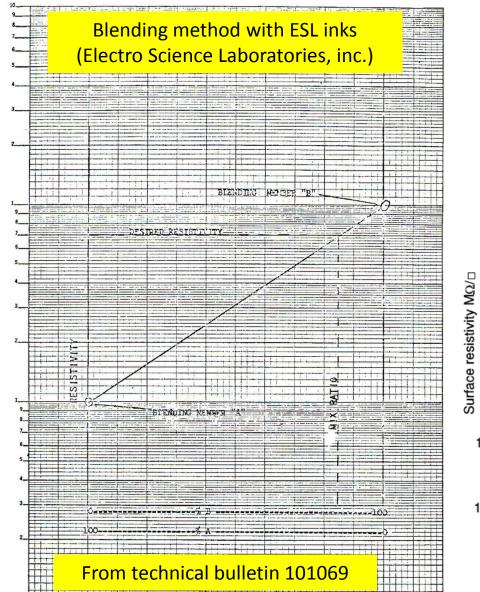
# Urgent tasks-2

- Define conceptual design of SuperFGD with a dedicated discussion/workshop
- Includes preliminary concepts about the electronics
- Timeline: July (??)
- Aim is to define a baseline design
- Describe design in a technical note

# Backup

### RESISTIVE INK SCREEN-PRINTING @ SACLAY TUNING OF THE PASTE RESISTIVITY

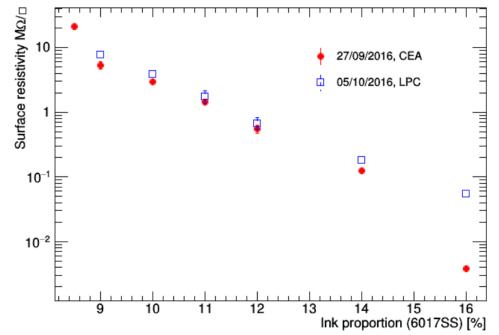




Tuning of resistivity by blending 2 inks of low and high resistivity. Tuning of the complete process is needed for MM0-SP1

### Tomuvol RPC (with CNRS/IN2P3/LPC)

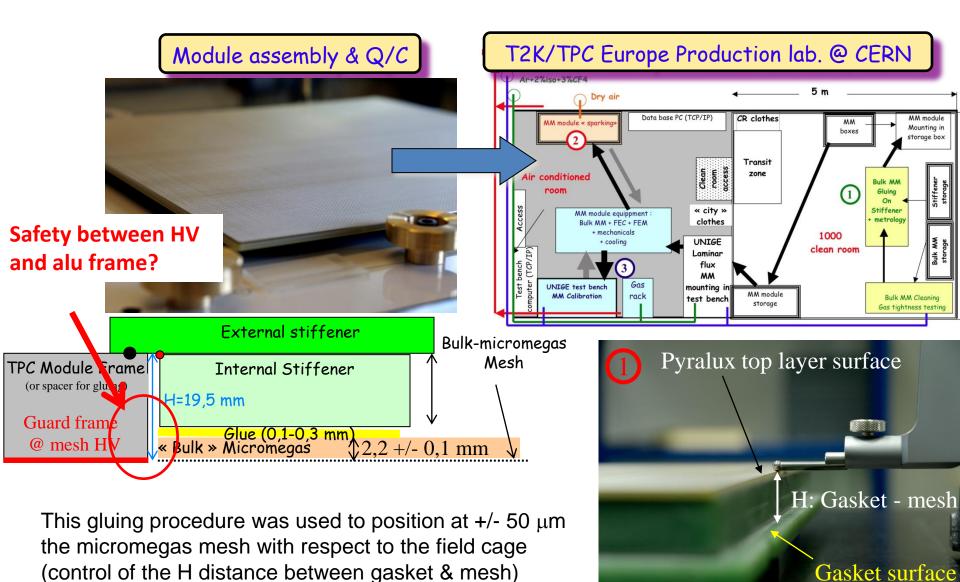
5 Mohm/square on 1 mm thick 50x60 cm<sup>2</sup> glass plates obtained with a bi-component Electrodag 6017SS+PM-404TM ink



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Control of the micromegas mesh alignment with the field cage last strip : use same gluing procedure as for the current ND280 TPCs ?





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